



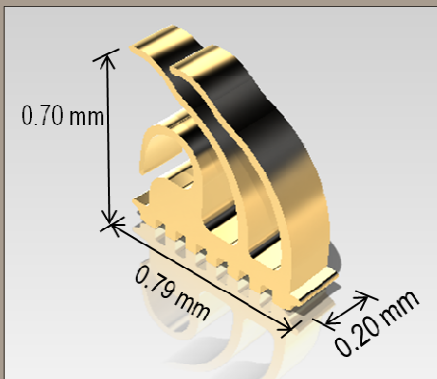
Low Profile Pin Model LPP-DA-1

FEATURES:

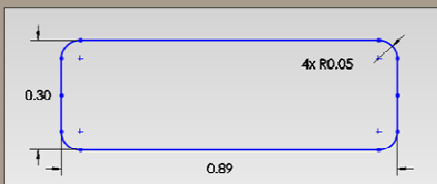
- Minimize Component Height above board
- Surface Mount
- Contact Material – Hard Gold
- Low Contact Resistance
- High Contact Force

APPLICATIONS:

- Micro Sockets
- Micro Connectors
- More



LPP-DA-1 Pin dimensions



LPP-DA-1 Pin Pad Dimensions (mm)

Provisional Specifications

MECHANICAL CHARACTERISTICS:

Contact Travel Length	> 0.125	mm
Contact Scrub Length (with contact travel of 0.125mm).....	> 0.075	mm
Contact Force (with contact travel of 0.125mm).....	> 35	gram-force
Cycle Lifetime (1).....	> 10000	cycles
Solderability – Rework (1,2).....	> 3	reflow cycles

ELECTRICAL CHARACTERISTICS

Contact Resistance (with contact force of 10 gram-force).....	< 30	mΩ
Current (Maximum)	2	A
Voltage (Nominal)	5	V
Characteristic Impedence (Differential)	71	ohms
Ground/Signal/Ground configuration with 0.74mm spacing		
RF Response (Rise Time Degradation) (3)	<10	%

ENVIRONMENTAL:

Operate Temperature	-55 to 175	°C
Humidity (non-condensing)	5 to 95	% RH

MATERIALS:

Body	NiFe (80/20)
Contact	Hard Gold

PHYSICAL CHARACTERISTICS:

Dimensions (LxWxH)	0.79 x 0.2 x 0.7	mm
Mass	~ 0.3	mg
ROHS Compliant ?	Yes	

Note 1. Further investigation required.

Note 2. SMIC Solder M705-GRN360-MZ

Note 3. Reference Signal Rise time : 60 psec – 20%-80%

Note that the information on this data sheet is for reference only. Please verify the specifications by consulting our engineering department.